

Refine Search

Search Results -

Terms	Documents
L1 and (cmp or polishing or planarizing or planarization or polish)	399

Database:

US Pre-Grant Publication Full-Text Database
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Search:

L5

Search History

DATE: Tuesday, February 07, 2006 [Printable Copy](#) [Create Case](#)

<u>Set</u> <u>Name</u> <u>Query</u> side by side	<u>Hit</u> <u>Count</u>	<u>Set</u> <u>Name</u> result set
<i>DB=PGPB,USPT,USOC; PLUR=YES; OP=ADJ</i>		
<u>L5</u> L1 and (cmp or polishing or planarizing or planarization or polish)	399	<u>L5</u>
<u>L4</u> L2 and (cmp or polishing or planarizing or planarization or polish)	0	<u>L4</u>
<i>DB=EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ</i>		
<u>L3</u> L2 and (cmp or polishing or planarizing or planarization or polish)	4	<u>L3</u>
<u>L2</u> L1	53	<u>L2</u>
<i>DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ</i>		
<u>L1</u> (collection near3 particle or primary near2 (size or diameter) or crystallite near2 (size or diameter)) with (nm or nanometer) and size near3 distribution	2155	<u>L1</u>

END OF SEARCH HISTORY